

Electrically Conductive Adhesive-Free Interconnection of Shingle Solar Cells

Julian Weber and Torsten Rößler

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Interconnection of Shingle Solar Cells by an Electrically Conductive Adhesive (ECA)

State of research

- In various studies, ECA amount is varied [1-5]
- Typically, ECA is applied as dots or dashes instead of a continuous line
- Consensus that extreme ECA reduction will compromise module output power





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- [3] Tune et al. "Electrically conductive adhesive interconnects: how low can you go?". 38th European Photovoltaic Solar Energy Conference and Exhibition (EUPVSC), pp. 735–738, 2021.
- [4] Carrière et al. "Toward shingling interconnection with SHJ solar cells". 37th European Photovoltaic Solar Energy Conference and Exhibition (EUPVSC), pp. 840–844. 2020.
- [5] Park et al. "Optimization of shingled-type lightweight glass-free solar modules for building integrated photovoltaics". Applied Sciences, vol. 12, art. 5011, 2022.
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Even without ECA, decent interconnection can be formed. How is that possible?

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Effect of ECA Reduction on the Interconnection Quality Summary

Presented findings

- At an ECA dash, lamination can turn poor into decent shingle interconnection
- At gaps between ECA-dashes and inside shingle joints with no ECA at all, lamination can form a busbar-to-busbar contact

Further findings in the proceedings paper

- For shingle joints with a continuous ECA line, lamination can enhance interconnection quality
- Laminated strings without ECA, with continuous ECA lines, or ECA dashes feature similar interconnection quality





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Can omitting the usage of ECA be an alternative approach for shingle interconnection?



Aging of ECA-Free Shingle Strings Methodology

Bill of materials for lamination

- Front glass (3 mm · 725 mm · 700 mm)
- Ethylene-vinyl-acetat (EVA) encapsulation foil
- Polyethylene-terephthalate (PET) back sheet

"T"-shaped coated copper foil as edge connector (attached with ECA)



Passivated emitter and rear cell (PERC) G1 shingles with

0.5 mm wide front and 1.2 mm wide back busbar



are given in the proceedings paper

* Simplified with respect to IEC standards 61215-219 and 62782,

details

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Aging tests*

- 200 temperature cycles (TC200)
- 1000 h of damp heat (DH1000)
- Dynamic mechanical load (DML)

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Characterization before and after aging

- I-V measurements (standard testing conditions)
- EL measurements
- MFI measurements

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"T"-shaped coated copper foil as edge connector (attached with ECA)



Passivated emitter and rear cell (PERC) G1 shingles with 0.5 mm wide front and 1.2 mm wide back busbar



200 Temperature Cycles (TC200) & 1000 h of Damp Heat (DH1000)

Results

 Before aging, no significant difference between ECA-containing reference strings and ECA-free strings in terms of P_{MPP}*



* Power at maximum power point $P_{\rm MPP}$ is not an ideal quantity to assess the interconnection quality [1]



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- Significant power loss due to TC200 for the ECA-free strings (interconnection quality fluctuates strongly among strings)

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- ····· 0.95 times average P_{MPP} before TC200 / DH1000
- ◆ After TC200 / DH1000



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- Before TC200 / DH1000
- Median
- ····· 0.95 times average P_{MPP} before TC200 / DH1000
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Aging of ECA-Free Shingle Strings Dynamic Mechanical Load (DML)

Methodology

- Laminate with 2 ECA-containing and 2 ECA-free strings (already subjected to DH1000) mounted at two edges
- 4 vacuum cups connected to a pneumatic cylinder placed on laminate surface
- 1000 push-pull cylces conducted with pressure of ±1 kPa (resulting in ±17 mm deflection)





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Results*

- Interconnection quality unaffected by DML according to
 - Dark *I–V* measurmeents
 - EL measurements
 - MFI measurements





* Details are given in the proceedings paper

- New insights into shingle joint properties
 - Lamination can enhance interconnection quality at ECA lines or ECA dashes
 - Strings without ECA, with ECA lines or ECA dashes feature similar interconnection quality (due to busbar-to-busbar contacts in ECA-free regions formed during lamination)





- New insights into shingle joint properties
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 - Strings without ECA, with ECA lines or ECA dashes feature similar interconnection quality (due to busbar-to-busbar contacts in ECA-free regions formed during lamination)
- New ECA-free interconnection approach based on direct busbar-to-busbar contacts
 - Only minor compromises in terms of TC200, DH1000, and DML test







Slide 32

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 - Another ECA-free, silver-saving interconnection approach by Fraunhofer ISE





- Paschen et al. "FoilMet[®]-Interconnect Shingling (FIS): aluminum foil based interconnection for modules with shingled solar cells". 38th European Photovoltaic Solar Energy Conference and Exhibition (EUPVSC), pp. 547–549, 2021.
- [2] Paschen et al. "FoilMet[®]-Interconnect: busbarless, electrically conductive adhesive-free, and solder-free aluminum interconnection for modules with shingled solar cells". Progress in Photovoltaics: Research and Applications, vol. 30, pp. 889–898, 2022.



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 - Advantages
 - No ECA application, ECA-to-busbar alignment, and ECA curing





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 - Advantages
 - No ECA application, ECA-to-busbar alignment, and ECA curing
 - Further development
 - Quantification of interconnection quality and respective cell-to-module loss
 - Enhancement of TC-stability





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Thank you for your attention!

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